CLAIMS:

1. An antifungal composition for human nails comprising an aqueous solution of a fluoride ion donor compound in combination with a wetting agent, the composition having a pH ranging from about 2.8 to about 3.5.

2. The composition of claim 1 wherein the fluoride donor compound is selected from the group consisting of stannous fluoride, stannic fluoride, hydrogen fluoride and dilute hydrofluoric acid.

3. The composition of claim 1 wherein the wetting agent is an alcohol.

4. The composition of claim 3 wherein the alcohol is selected from the group consisting of methanol, ethanol and isopropanol.

5. The composition of claim 2 wherein the aqueous solution is saturated with a fluoride donor compound selected from the group consisting of stannous fluoride and stannic fluoride at ambient conditions.

6. The composition of claim 1 comprising up to about 20 weight percent wetting agent.

7. The composition of claim 2 comprising from about 15 to about 20 weight percent wetting agent.

8. The composition of claim 3 comprising up to about 20 weight percent alcohol.

9. A method for treating fungal growth areas proximal to a human nail, the method comprising the steps of:

providing an aqueous solution substantially saturated with a fluorine ion donor compound and comprising up to about 20 weight percent of a wetting agent and a pH ranging from about 2.8 to about 3.5; and

periodically topically applying the aqueous solution to the fungal growth areas.

10. The method of claim 9 wherein the fluorine ion donor compound is selected from the group consisting of stannous fluoride, stannic fluoride and hydrogen fluoride or dilute hydrofluoric acid.

11. The method of claim 9 wherein the wetting agent is selected from the group consisting of methanol, ethanol and isopropanol.

12. The method of claim 9 wherein the solution comprises from about 15 to about 20 weight percent wetting agent.

13. The method of claim 9 wherein the aqueous solution comprises from about 15 to about 20 weight percent alcohol as the wetting agent.

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